

L Number	Hits	Search Text	DB	Time stamp
1	1	6242799.URPN.	USPAT	2002/10/04 07:44
2	15	("5264726" "5468681" "5474458" "5561321" "5660917" "5734201" "5847456" "5854534" "5874175" "5920123" "5943212" "5986338" "6011312" "6034437" "6084297").PN.	USPAT	2002/10/04 07:45
3	1994039	(polyimide (stress adj relax\$4) polymeric polymer elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:57
4	17478	csp (chip adj (size sized scale scaled))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:57
5	1995522	(polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:58
6	45144	((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:16
7	160	(csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 08:04
8	153	((csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester)))) and (chip die semiconductor wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:19
9	0	6352775.URPN.	USPAT	2002/10/04 08:37
10	0	6147311.URPN.	USPAT	2002/10/04 08:42
11	3	("5461775" "5677576" "5744758").PN.	USPAT	2002/10/04 08:42

12	92	(US-6197613-\$ or US-6181569-\$ or US-6277669-\$ or US-6159837-\$ or US-6350633-\$ or US-6350632-\$ or US-6350386-\$ or US-5925931-\$ or US-5604379-\$ or US-6287893-\$ or US-6111317-\$ or US-5834844-\$ or US-5539153-\$ or US-6255737-\$ or US-6323542-\$ or US-6200888-\$ or US-6372527-\$ or US-6284563-\$ or US-6211572-\$ or US-5760465-\$ or US-5874782-\$ or US-5666270-\$ or US-4813129-\$ or US-6007349-\$ or US-5855063-\$ or US-5984692-\$).did. or (US-5738530-\$ or US-5525065-\$ or US-5415555-\$ or US-5326412-\$ or US-6333565-\$ or US-5147208-\$ or US-4740700-\$ or US-4116517-\$ or US-6265671-\$ or US-5638599-\$ or US-5653892-\$ or US-5608254-\$ or US-5603848-\$ or US-6307159-\$ or US-4548451-\$ or US-5984691-\$ or US-6024580-\$ or US-6071137-\$ or US-5813876-\$ or US-5759047-\$ or US-5575662-\$ or US-6214923-\$ or US-6335416-\$ or US-5529504-\$ or US-5938452-\$ or US-6403460-\$ or US-5422516-\$).did. or (US-6066512-\$ or US-6130116-\$ or US-5077598-\$ or US-6165886-\$ or US-6066808-\$ or US-5829124-\$ or US-H001153-\$ or US-5323947-\$ or US-5252852-\$ or US-5521994-\$ or US-6395582-\$ or US-6323065-\$ or US-6303219-\$ or US-6259154-\$ or US-6201298-\$ or US-6194778-\$ or US-6097085-\$ or US-6051450-\$ or US-5998241-\$ or US-5786239-\$ or US-5663530-\$ or US-5397921-\$ or US-5661086-\$ or US-5763294-\$ or US-5474957-\$ or US-5877043-\$ or US-5756377-\$).did. or (US-5602059-\$ or US-5973389-\$ or US-6388458-\$ or US-6242799-\$ or US-6456100-\$ or US-6306688-\$ or US-6284353-\$).did. or (US-20020006718-\$ or US-20010019852-\$ or US-20020066584-\$ or US-20010004943-\$ or US-20020090754-\$).did.	USPAT; US-PGPUB	2002/10/04 09:43
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13	37	((US-6197613-\$ or US-6181569-\$ or US-6277669-\$ or US-6159837-\$ or US-6350633-\$ or US-6350632-\$ or US-6350386-\$ or US-5925931-\$ or US-5604379-\$ or US-6287893-\$ or US-6111317-\$ or US-5834844-\$ or US-5539153-\$ or US-6255737-\$ or US-6323542-\$ or US-6200888-\$ or US-6372527-\$ or US-6284563-\$ or US-6211572-\$ or US-5760465-\$ or US-5874782-\$ or US-5666270-\$ or US-4813129-\$ or US-6007349-\$ or US-5855063-\$ or US-5984692-\$).did. or (US-5738530-\$ or US-5525065-\$ or US-5415555-\$ or US-5326412-\$ or US-6333565-\$ or US-5147208-\$ or US-4740700-\$ or US-4116517-\$ or US-6265671-\$ or US-5638599-\$ or US-5653892-\$ or US-5608254-\$ or US-5603848-\$ or US-6307159-\$ or US-4548451-\$ or US-5984691-\$ or US-6024580-\$ or US-6071137-\$ or US-5813876-\$ or US-5759047-\$ or US-5575662-\$ or US-6214923-\$ or US-6335416-\$ or US-5529504-\$ or US-5938452-\$ or US-6403460-\$ or US-5422516-\$).did. or (US-6066512-\$ or US-6130116-\$ or US-5077598-\$ or US-6165886-\$ or US-6066808-\$ or US-5829124-\$ or US-H001153-\$ or US-5323947-\$ or US-5252852-\$ or US-5521994-\$ or US-6395582-\$ or US-6323065-\$ or US-6303219-\$ or US-6259154-\$ or US-6201298-\$ or US-6194778-\$ or US-6097085-\$ or US-6051450-\$ or US-5998241-\$ or US-5786239-\$ or US-5663530-\$ or US-5397921-\$ or US-5661086-\$ or US-5763294-\$ or US-5474957-\$ or US-5877043-\$ or US-5756377-\$).did. or (US-5602059-\$ or US-5973389-\$ or US-6388458-\$ or US-6242799-\$ or US-6456100-\$ or US-6306688-\$ or US-6284353-\$).did. or (US-20020006718-\$ or US-20010019852-\$ or US-20020066584-\$ or US-20010004943-\$ or US-20020090754-\$).did.) and (particles filler)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 09:45
14	1	6323542.URPN.	USPAT	2002/10/04 09:52
15	0	6441473.URPN.	USPAT	2002/10/04 09:54
16	12	("5148266" "5346861" "5679977" "5682061" "5801446" "5848467" "5994781" "6028354" "6150194" "6211572" "6239489" "6323542").PN.	USPAT	2002/10/04 09:54
17	12	("5148266" "5346861" "5679977" "5682061" "5801446" "5848467" "5994781" "6028354" "6150194" "6211572" "6239489" "6323542").PN.	USPAT	2002/10/04 10:07
18	7	("5126820" "5148266" "5563102" "5641113" "5656863" "5753974" "5834844").PN.	USPAT	2002/10/04 10:07
19	317094	(depression adj layer) (stress near1 (absorb\$3 absorption relieving reducing reduce relieve)) compliant elastomer elastomeric (elastic adj layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:16

20	44856	((depression adj layer) (stress near1 (absorb\$3 absorption relieving reducing reduce relieve)) compliant elastomer elastomeric (elastic adj layer)) with (particles filler containing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:18
21	126	((csp (chip adj (size sized scale scaled))) and (((depression adj layer) (stress near1 (absorb\$3 absorption relieving reducing reduce relieve)) compliant elastomer elastomeric (elastic adj layer)) with (particles filler containing)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:18
22	97	((csp (chip adj (size sized scale scaled))) and (((depression adj layer) (stress near1 (absorb\$3 absorption relieving reducing reduce relieve)) compliant elastomer elastomeric (elastic adj layer)) with (particles filler containing))) not ((csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:19
23	93	((csp (chip adj (size sized scale scaled))) and (((depression adj layer) (stress near1 (absorb\$3 absorption relieving reducing reduce relieve)) compliant elastomer elastomeric (elastic adj layer)) with (particles filler containing))) not ((csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester)))) and (chip die semiconductor wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 10:19

L Number	Hits	Search Text	DB	Time stamp
1	1	6242799.URPN.	USPAT	2002/10/04 07:44
2	15	("5264726" "5468681" "5474458" "5561321" "5660917" "5734201" "5847456" "5854534" "5874175" "5920123" "5943212" "5986338" "6011312" "6034437" "6084297").PN.	USPAT	2002/10/04 07:45
3	1994039	(polyimide (stress adj relax\$4) polymeric polymer elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:57
4	17478	csp (chip adj (size sized scale scaled))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:57
5	1995522	(polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:58
6	45144	((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 08:02
7	160	(csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 08:04
8	153	((csp (chip adj (size sized scale scaled))) and (((polyimide (stress adj (relaxation relaxing)) polymeric polymer elastic)) with ((particles filler) with (silica resin silicone alumina boron nitride ester imide acrylic polyester)))) and (chip die semiconductor wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 08:04
9	0	6352775.URPN.	USPAT	2002/10/04 08:37
10	0	6147311.URPN.	USPAT	2002/10/04 08:42
11	3	("5461775" "5677576" "5744758").PN.	USPAT	2002/10/04 08:42
-	7	polyimide near3 ((elastic near1 modulus) near3 (range about))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:03
-	85	polyimide near3 (elastic near1 modulus)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/03 16:05
-	12	(polyimide near3 (elastic near1 modulus)) with (range about)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:47
-	5	((polyimide near3 (elastic near1 modulus)) with (range about)) not (polyimide near3 ((elastic near1 modulus) near3 (range about)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:06
-	11	(polyimide near3 (elastic near1 modulus)) with gpa	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:07
-	4	((polyimide near3 (elastic near1 modulus)) with gpa) not (polyimide near3 ((elastic near1 modulus) near3 (range about)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:07

-	15	(polyimide near3 (elastic near1 modulus)) and gpa	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:07
-	6	((polyimide near3 (elastic near1 modulus)) and gpa) not ((polyimide near3 (elastic near1 modulus)) with (range about))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:27
-	4627	(csp (chip adj (size\$1 scale\$1) adj (package packaging device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 22:55
-	0	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) and (tress near1 buffer\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:34
-	20	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) and (stress near1 buffer\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 09:34
-	4	("6163463" "6187615" "6187680" "6197613").PN.	USPAT	2002/07/14 22:19
-	10	("5143865" "5668405" "5757078" "5789142" "5883435" "5895229" "5946590" "6022757" "6028011" "6028357").PN.	USPAT	2002/03/08 09:50
-	1	"6175151"	USPAT	2002/03/08 10:00
-	1	6175151.pn. and "154"	USPAT	2002/03/08 10:02
-	1	6175151.pn. and polyimide	USPAT	2002/03/08 10:02
-	1	6181569.URPN.	USPAT	2002/03/08 10:16
-	17	"5925931"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 10:28
-	8	("4720738" "4984061" "5394013" "5604379" "5661344" "5719439" "5757078" "5801446").PN.	USPAT	2002/03/08 10:31
-	30	5604379.URPN.	USPAT	2002/03/08 10:33
-	19	("4462534" "5024372" "5220200" "5261593" "5293067" "5346861" "5388327" "5455390" "5504277" "5539153" "5541450" "5547740" "5564617" "5604379" "5608262" "5701032" "5736456" "5777391" "5814894").PN.	USPAT	2002/03/08 10:40
-	1	6111317.URPN.	USPAT	2002/03/08 10:44
-	16	("5046161" "5272111" "5394013" "5448114" "5604379" "5631499" "5656858" "5677576" "5719448" "5757078" "5773888" "5834844" "5844304" "5883435" "5886415" "5903058").PN.	USPAT	2002/03/08 10:45
-	2450	polyimide near2 photosensitive	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 16:37
-	7031	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) (polyimide near2 photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 16:37
-	46	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) and (polyimide near2 photosensitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:52

-	11	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) and pyrolysis	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 16:50
-	0	((csp (chip adj (size\$1 scale\$1) adj (package packaging device)))) and (pyrolysis with polyimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/03/08 16:46
-	3	(semiconductor nearer1 (package device)) and (polyimide near3 pyrolysis near3 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:46
-	1	6277669.URPN.	USPAT	2002/06/14 10:56
-	1	6277669.URPN.	USPAT	2002/06/14 10:58
-	4	("6163463" "6187615" "6187680" "6197613").PN.	USPAT	2002/06/14 10:58
-	9	"5852326"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/14 11:00
-	51	"5679977"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/14 11:01
-	2	"5959355"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/14 11:01
-	58	"5852326" "5679977" "5959355"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/14 11:02
-	20	("5852326" "5679977" "5959355") and (thermal near1 stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/14 11:02
-	0	6284563.URPN.	USPAT	2002/06/14 11:07
-	11	("4813129" "4885126" "4902606" "5072520" "5180311" "5666270" "5679977" "5749997" "5777379" "5874782" "6043563").PN.	USPAT	2002/06/14 11:07
-	3	5874782.URPN.	USPAT	2002/06/14 11:08
-	1	6211572.URPN.	USPAT	2002/06/14 11:08
-	22	("4001870" "4074342" "4365264" "4618878" "4813129" "4885126" "4902606" "5072520" "5148265" "5148266" "5180311" "5430329" "5455390" "5489749" "5491302" "5604380" "5619017" "5666270" "5679977" "5749997" "5777379" "5874782").PN.	USPAT	2002/06/14 12:33
-	9	5666270.URPN.	USPAT	2002/06/14 12:37
-	2	("4999460" "5001302").PN.	USPAT	2002/06/14 12:38
-	35	4813129.URPN.	USPAT	2002/06/14 12:41
-	3	6007349.URPN.	USPAT	2002/06/14 12:43
-	0	6307159.URPN.	USPAT	2002/06/14 12:44
-	5	("5049085" "5362241" "5971253" "6007349" "6042387").PN.	USPAT	2002/06/14 12:44
-	1	5984692.URPN.	USPAT	2002/06/14 12:46

-	4	("4647126" "4673967" "4813129" "5007872").PN.	USPAT	2002/06/14 12:46
-	8	5415555.URPN.	USPAT	2002/06/14 12:48
-	8	5415555.URPN.	USPAT	2002/06/14 12:49
-	13	("4116517" "4125310" "4268956" "4403272" "4453795" "4740700" "4813129" "4902606" "5129142" "5147208" "5158466" "5172050" "5207585").PN.	USPAT	2002/06/14 12:49
-	61	4740700.URPN.	USPAT	2002/06/14 12:50
-	0	6083557.URPN.	USPAT	2002/06/14 12:52
-	38	("3301707" "3359192" "4048349" "4080532" "4139444" "4662984" "4678536" "4705593" "4740700" "4745278" "4792681" "4871416" "4926051" "4927771" "5030827" "5115442" "5183531" "5238529" "5279702" "5312516" "5374330" "5424544" "5426304" "5436450" "5460687" "5466331" "5466332" "5532484" "5574282" "5602392" "5603848" "5608254" "5629665" "5638599" "5653892" "5654580" "5679267" "5804836").PN.	USPAT	2002/06/14 12:53
-	4	("6163463" "6187615" "6187680" "6197613").PN.	USPAT	2002/06/15 11:35
-	1	6277669.URPN.	USPAT	2002/06/15 11:35
-	11	("4813129" "4885126" "4902606" "5072520" "5180311" "5666270" "5679977" "5749997" "5777379" "5874782" "6043563").PN.	USPAT	2002/06/15 11:35
-	9	5666270.URPN.	USPAT	2002/06/15 11:37
-	2	("4999460" "5001302").PN.	USPAT	2002/06/15 11:37
-	35	4813129.URPN.	USPAT	2002/06/15 11:38
-	20	("3870978" "3971610" "4548451" "4770641" "4813129" "5123849" "5147208" "5158466" "5194698" "5197184" "5207887" "5233157" "5245750" "5264787" "5288235" "5339027" "5342207" "5364277" "5390412" "5413659").PN.	USPAT	2002/06/15 11:41
-	18	5147208.URPN.	USPAT	2002/06/15 11:43
-	0	6071137.URPN.	USPAT	2002/06/15 11:44
-	23	("3795888" "4060295" "4542950" "4629270" "4648668" "4886461" "5061192" "5071357" "5102343" "5137461" "5147208" "5181853" "5185073" "5222668" "5228862" "5230632" "5237743" "5322719" "5409392" "5505625" "5657972" "5808474" "5813876").PN.	USPAT	2002/06/15 11:44
-	6	("3114587" "4116517" "4871315" "4911653" "5147208" "5372512").PN.	USPAT	2002/06/15 11:45
-	6	("3114587" "4116517" "4871315" "4911653" "5147208" "5372512").PN.	USPAT	2002/06/15 11:46
-	0	6024580.URPN.	USPAT	2002/06/15 11:46
-	0	6024580.URPN.	USPAT	2002/06/15 11:46
-	7	5984691.URPN.	USPAT	2002/06/15 11:48

-	17	("3971610" "4050756" "4548451" "4954878" "4991290" "5033675" "5041183" "5069628" "5095628" "5147208" "5207585" "5248261" "5261826" "5759047" "5808873" "5819406" "5880590").PN.	USPAT	2002/06/15 11:49
-	39	5207585.URPN.	USPAT	2002/06/15 11:51
-	7	5529504.URPN.	USPAT	2002/06/15 11:53
-	3	5938452.URPN.	USPAT	2002/06/15 11:54
-	16	("4628406" "4641222" "4835704" "4845542" "4847146" "4874721" "4894115" "5161093" "5352926" "5449427" "5454904" "5473119" "5502002" "5527741" "5529504" "5731073").PN.	USPAT	2002/06/15 11:55
-	13	("4249302" "4553192" "4915983" "5136359" "5147210" "5187020" "5188702" "5197892" "5207585" "5374196" "5395253" "5417577" "5434452").PN.	USPAT	2002/06/15 11:57
-	21	("3401126" "3429040" "3541222" "3634807" "3654585" "3680037" "3806801" "3862790" "3971610" "4027935" "4038599" "4184729" "4581679" "4707657" "4793814" "4837507" "4991290" "5020219" "5061192" "5069628" "5133119").PN.	USPAT	2002/06/15 11:58
-	17	("3971610" "4050756" "4548451" "4954878" "4991290" "5033675" "5041183" "5069628" "5095628" "5147208" "5207585" "5248261" "5261826" "5759047" "5808873" "5819406" "5880590").PN.	USPAT	2002/06/15 12:00
-	8	5575662.URPN.	USPAT	2002/06/15 12:02
-	6	("4184729" "4453795" "4948374" "5069628" "5147208" "5354205").PN.	USPAT	2002/06/15 12:04
-	13	5288235.URPN.	USPAT	2002/06/15 12:29
-	14	5525065.URPN.	USPAT	2002/06/15 12:29
-	52	4548451.URPN.	USPAT	2002/06/15 12:33
-	2	5738530.URPN.	USPAT	2002/06/15 12:35
-	16	("3870978" "3971610" "4050756" "4548451" "4770641" "4813129" "5123849" "5158466" "5194698" "5197184" "5207887" "5233157" "5245750" "5264787" "5339027" "5364277").PN.	USPAT	2002/06/15 12:35
-	12	5326412.URPN.	USPAT	2002/06/15 12:44
-	5	("4116517" "4125310" "4125441" "4453795" "4813129").PN.	USPAT	2002/06/15 12:45
-	6	("3880486" "3986255" "4125310" "4403272" "4548451" "4581679").PN.	USPAT	2002/06/15 12:47
-	11	("4813129" "4885126" "4902606" "5072520" "5180311" "5666270" "5679977" "5749997" "5777379" "5874782" "6043563").PN.	USPAT	2002/06/15 12:48
-	0	6265671.URPN.	USPAT	2002/06/15 12:50
-	5	("4740700" "5153051" "5243142" "5252195" "5478972").PN.	USPAT	2002/06/15 12:50
-	3	5638599.URPN.	USPAT	2002/06/15 12:52

-	3	5638599.URPN.	USPAT	2002/06/15 12:52
-	12	("4080532" "4740700" "4745278" "4792681" "5235195" "5424544" "5426303" "5426304" "5436450" "5457318" "5472913" "5478242").PN.	USPAT	2002/06/15 12:52
-	9268	semiconductor and (coefficient near1 thermal near1 expansion)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:20
-	1471	(semiconductor and (coefficient near1 thermal near1 expansion)) and (solder adj (ball bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:20
-	31	((semiconductor and (coefficient near1 thermal near1 expansion)) and (solder adj (ball bump))) and (interconnection near1 reliability)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:22
-	1399	((semiconductor and (coefficient near1 thermal near1 expansion)) and (solder adj (ball bump))) and (substrate (printed adj circuit adj board) pcb)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:23
-	2	((semiconductor and (coefficient near1 thermal near1 expansion)) and (solder adj (ball bump))) and (substrate (printed adj circuit adj board) pcb) and (thermal near1 stress near1 absorbing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:24
-	14	(semiconductor and (coefficient near1 thermal near1 expansion)) and (thermal near1 stress near1 absorbing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:28
-	71	semiconductor and (thermal near1 stress near1 absorbing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 14:27
-	10	("3373481" "4173768" "4250520" "4545610" "4673772" "4818728" "4845542" "4930001" "5151773" "5189507").PN.	USPAT	2002/06/15 13:38
-	4	semiconductor and (thermal near1 stress near1 absorbing)and HASHIMOTO-NOBUAKI	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:44
-	129	semiconductor and HASHIMOTO-NOBUAKI	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 13:44
-	28	semiconductor and HASHIMOTO-NOBUAKI	USPAT	2002/06/15 13:45
-	0	6333565.URPN.	USPAT	2002/06/15 13:46
-	6	("5077598" "5086337" "5189505" "5659952" "5776796" "6130116").PN.	USPAT	2002/06/15 13:46
-	12	5077598.URPN.	USPAT	2002/06/15 13:47
-	9	("3030558" "3596228" "4070688" "4215359" "4647959" "4710798" "4845542" "4871921" "4893172").PN.	USPAT	2002/06/15 13:48
-	0	6323542.URPN.	USPAT	2002/06/15 13:50
-	7	("5126820" "5148266" "5563102" "5641113" "5656863" "5753974" "5834844").PN.	USPAT	2002/06/15 13:50
-	4	6144507.URPN.	USPAT	2002/06/15 14:23
-	3	("4760440" "5134340" "5847650").PN.	USPAT	2002/06/15 14:23
-	8	(solder adj (bump ball)) and (thermal near1 stress near1 absorbing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:06

-	21	(bump ball) and (thermal near1 stress near1 absorbing)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/15 14:29
-	2961	elongat\$3 near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:45
-	470	(elongat\$3 near2 pad) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:06
-	56	((elongat\$3 near2 pad) and (bump ball)) and thermal and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:38
-	119	((elongat\$3 near2 pad) and (bump ball)) and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:38
-	63	((elongat\$3 near2 pad) and (bump ball)) and stress) not ((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:39
-	3	((elongat\$3 near2 pad) and (bump ball)) and stress) not ((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)) and (solder adj (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:39
-	2914	(elongated elongating elongate) near2 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:55
-	1729	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:20
-	342	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))) and (elastic\$3 modulus)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:48
-	88	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))) and (elastic\$3 modulus)) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:21
-	68	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))) and (elastic\$3 modulus)) and (bump ball)) not ((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:48
-	5	((elongated elongating elongate) near2 pad) and ((csp (chip near1 (size\$1 scale\$1) near1(package packaging device))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 07:53
-	110	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:21
-	64	((elongated elongating elongate) near2 pad) and (semiconductor nearer1 (package device))) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:58
-	0	6121784.URPN.	USPAT	2002/06/17 09:31
-	9	("4480223" "4523144" "4528914" "4563640" "4780670" "4998062" "5091692" "5126662" "5280236").PN.	USPAT	2002/06/17 09:31

-	26	("3424698" "3781596" "3832769" "3986939" "4016050" "4393576" "4648179" "4832255" "4851614" "4879156" "5015538" "5113579" "5116459" "5239448" "5305523" "5306872" "5323947" "5338900" "5356526" "5384952" "5611140" "5640052" "5734560" "5764485" "5819401" "5829124").PN.	USPAT	2002/06/17 09:32
-	31	5323947.URPN.	USPAT	2002/06/17 09:34
-	311	(elongated elongating elongate) with ((bond bonding) adj pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:56
-	279450	"311" not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (elastic\$3 modulus)) and (bump ball)) not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:57
-	280	((elongated elongating elongate) with ((bond bonding) adj pad)) not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (elastic\$3 modulus)) and (bump ball)) not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (bump ball))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:58
-	84	((elongated elongating elongate) with ((bond bonding) adj pad)) not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (elastic\$3 modulus)) and (bump ball)) not (((elongat\$3 near2 pad) and (bump ball)) and thermal and stress)) not ((((elongated elongating elongate) near2 pad) and (semiconductor near1 (package device))) and (bump ball))) and (bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/06/17 09:59
-	3	5252852.URPN.	USPAT	2002/06/17 10:06
-	3	("4034399" "4857746" "4912545").PN.	USPAT	2002/06/17 10:07
-	7	"5998241"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:06
-	3	"6303219"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:06
-	7	"6122171"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:07

-	3	"6060782"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:07
-	14	"5786239"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:09
-	4	"6201298"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:10
-	19	"5835355"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:15
-	11	"5929517"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:19
-	66	"5998241" "6303219" "6122171" "6060782" "5786239" "6201298" "5835355" "5929517"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 21:20
-	0	6395582.URPN.	USPAT	2002/07/14 21:21
-	18	("5240588" "5397921" "5420460" "5455456" "5583378" "5633533" "5640047" "5663530" "5710459" "5739581" "5832596" "5844168" "5972736" "5976916" "5998241" "6066512" "6248612" "6258631").PN.	USPAT	2002/07/14 21:21
-	8	("5023202" "5083191" "5442232" "5518964" "5661086" "5785535" "5804872" "5901041").PN.	USPAT	2002/07/14 21:22
-	3	("4980219" "4981817" "5182851").PN.	USPAT	2002/07/14 21:24
-	32	5661086.URPN.	USPAT	2002/07/14 21:24
-	8	("4843808" "5016084" "5244838" "5474957" "5492866" "5786239" "5877042" "5909056").PN.	USPAT	2002/07/14 21:27
-	10	("3801388" "4209355" "4695527" "4973562" "5223454" "5316894" "5336650" "5352632" "5559372" "5633535").PN.	USPAT	2002/07/14 21:28
-	47	5474957.URPN.	USPAT	2002/07/14 21:29
-	5	5877043.URPN.	USPAT	2002/07/14 21:31
-	13	("4873123" "5016084" "5168430" "5278724" "5340771" "5352632" "5383787" "5383788" "5386341" "5397921" "5435732" "5474957" "5756380").PN.	USPAT	2002/07/14 21:31
-	6	("4411719" "5212402" "5474957" "5518957" "5556907" "5661086").PN.	USPAT	2002/07/14 21:34
-	3	("5474957" "5578525" "5602059").PN.	USPAT	2002/07/14 21:35
-	4	("5353498" "5382546" "5383269" "5409865").PN.	USPAT	2002/07/14 21:36
-	23	5602059.URPN.	USPAT	2002/07/14 21:36
-	7	("5525834" "5612576" "5835355" "5841194" "5939778" "6002171" "6166434").PN.	USPAT	2002/07/14 21:41
-	19	"5760465"	USPAT	2002/07/14 22:19

-	4967	(csp (chip adj (size\$1 scale\$1) near (package packaging device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 22:57
-	2294	((csp (chip adj (size\$1 scale\$1) near (package packaging device)))) and (bump ball (external adj electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 22:59
-	232	((csp (chip adj (size\$1 scale\$1) near (package packaging device)))) and (bump ball (external adj electrode))) and passivation	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:00
-	191	((csp (chip adj (size\$1 scale\$1) near (package packaging device)))) and (bump ball (external adj electrode))) and passivation) and (intermediate polyimide polymer elastomer elastomeric)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:19
-	7	("5126820" "5148266" "5563102" "5641113" "5656863" "5753974" "5834844").PN.	USPAT	2002/07/14 23:08
-	23	("5243221" "5319246" "5416355" "5436410" "5457067" "5475268" "5525839" "5528061" "5530289" "5532516" "5534731" "5561327" "5614439" "5614767" "5656852" "5834844" "5861673" "5861674" "5942801" "5955787" "5962920" "5969409" "5981373").PN.	USPAT	2002/07/14 23:13
-	1	6255737.URPN.	USPAT	2002/07/14 23:13
-	3	"6323542"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:19
-	8	"6181569"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:19
-	5	"6211572"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:22
-	15	"6323542" "6181569" "6211572"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:22
-	2	"6333565"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/07/14 23:29
-	6	("5077598" "5086337" "5189505" "5659952" "5776796" "6130116").PN.	USPAT	2002/07/14 23:29

-	86	(US-6197613-\$ or US-6181569-\$ or US-6277669-\$ or US-6159837-\$ or US-6350633-\$ or US-6350632-\$ or US-6350386-\$ or US-5925931-\$ or US-5604379-\$ or US-6287893-\$ or US-6111317-\$ or US-5834844-\$ or US-5539153-\$ or US-6255737-\$ or US-6323542-\$ or US-6200888-\$ or US-6372527-\$ or US-6284563-\$ or US-6211572-\$ or US-5760465-\$ or US-5874782-\$ or US-5666270-\$ or US-4813129-\$ or US-6007349-\$ or US-5855063-\$ or US-5984692-\$).did. or (US-5738530-\$ or US-5525065-\$ or US-5415555-\$ or US-5326412-\$ or US-6333565-\$ or US-5147208-\$ or US-4740700-\$ or US-4116517-\$ or US-6265671-\$ or US-5638599-\$ or US-5653892-\$ or US-5608254-\$ or US-5603848-\$ or US-6307159-\$ or US-4548451-\$ or US-5984691-\$ or US-6024580-\$ or US-6071137-\$ or US-5813876-\$ or US-5759047-\$ or US-5575662-\$ or US-6214923-\$ or US-6335416-\$ or US-5529504-\$ or US-5938452-\$ or US-6403460-\$ or US-5422516-\$).did. or (US-6066512-\$ or US-6130116-\$ or US-5077598-\$ or US-6165886-\$ or US-6066808-\$ or US-5829124-\$ or US-H001153-\$ or US-5323947-\$ or US-5252852-\$ or US-5521994-\$ or US-6395582-\$ or US-6323065-\$ or US-6303219-\$ or US-6259154-\$ or US-6201298-\$ or US-6194778-\$ or US-6097085-\$ or US-6051450-\$ or US-5998241-\$ or US-5786239-\$ or US-5663530-\$ or US-5397921-\$ or US-5661086-\$ or US-5763294-\$ or US-5474957-\$ or US-5877043-\$ or US-5756377-\$).did. or (US-5602059-\$ or US-5973389-\$).did. or (US-20020006718-\$ or US-20010019852-\$ or US-20020066584-\$ or US-20010004943-\$).did.	USPAT; US-PGPUB	2002/10/03 16:04
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-	0	((US-6197613-\$ or US-6181569-\$ or US-6277669-\$ or US-6159837-\$ or US-6350633-\$ or US-6350632-\$ or US-6350386-\$ or US-5925931-\$ or US-5604379-\$ or US-6287893-\$ or US-6111317-\$ or US-5834844-\$ or US-5539153-\$ or US-6255737-\$ or US-6323542-\$ or US-6200888-\$ or US-6372527-\$ or US-6284563-\$ or US-6211572-\$ or US-5760465-\$ or US-5874782-\$ or US-5666270-\$ or US-4813129-\$ or US-6007349-\$ or US-5855063-\$ or US-5984692-\$).did. or (US-5738530-\$ or US-5525065-\$ or US-5415555-\$ or US-5326412-\$ or US-6333565-\$ or US-5147208-\$ or US-4740700-\$ or US-4116517-\$ or US-6265671-\$ or US-5638599-\$ or US-5653892-\$ or US-5608254-\$ or US-5603848-\$ or US-6307159-\$ or US-4548451-\$ or US-5984691-\$ or US-6024580-\$ or US-6071137-\$ or US-5813876-\$ or US-5759047-\$ or US-5575662-\$ or US-6214923-\$ or US-6335416-\$ or US-5529504-\$ or US-5938452-\$ or US-6403460-\$ or US-5422516-\$).did. or (US-6066512-\$ or US-6130116-\$ or US-5077598-\$ or US-6165886-\$ or US-6066808-\$ or US-5829124-\$ or US-H001153-\$ or US-5323947-\$ or US-5252852-\$ or US-5521994-\$ or US-6395582-\$ or US-6323065-\$ or US-6303219-\$ or US-6259154-\$ or US-6201298-\$ or US-6194778-\$ or US-6097085-\$ or US-6051450-\$ or US-5998241-\$ or US-5786239-\$ or US-5663530-\$ or US-5397921-\$ or US-5661086-\$ or US-5763294-\$ or US-5474957-\$ or US-5877043-\$ or US-5756377-\$).did. or (US-5602059-\$ or US-5973389-\$).did. or (US-20020006718-\$ or US-20010019852-\$ or US-20020066584-\$ or US-20010004943-\$).did.) and ((polyimide (stress adj relax\$4) polymeric polymer elastic) near3 (particles near3 (silica resin silicone alumina)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/03 16:19
-	4799	((polyimide (stress adj relax\$4) polymeric polymer elastic)) near3 (particles near3 (silica resin silicone alumina))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/03 16:20
-	6201	(csp (chip adj (size\$1 scale\$1) adj (package packaging device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/03 16:22
-	17506	csp (chip adj (size\$1 scale\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:56
-	7	((polyimide (stress adj relax\$4) polymeric polymer elastic)) near3 (particles near3 (silica resin silicone alumina))) and ((csp (chip adj (size\$1 scale\$1) adj (package packaging device))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/03 16:22
-	17	((polyimide (stress adj relax\$4) polymeric polymer elastic)) near3 (particles near3 (silica resin silicone alumina))) and (csp (chip adj (size\$1 scale\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2002/10/04 07:58

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	2	"6255737"	USPAT; US-PGPUB; EPO; JPO; DERWENT
2	BRS	L3	4697	(csp (chip near (size\$1 scale\$1) near2 package))	USPAT; US-PGPUB; EPO; JPO; DERWENT
3	BRS	L4	83	3 same (elastomer (elasticity near layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT
4	BRS	L6	119	3 same (elastomer\$2 ((elasticity compliant) near layer))	USPAT; US-PGPUB; EPO; JPO; DERWENT
5	BRS	L14	25	4109096.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT
6	BRS	L16	5	6028354.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT
7	BRS	L18	0	6239489.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT
8	BRS	L20	4316	(elastomer\$2 ((elasticity compliant) near layer)) near4 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT
9	BRS	L21	14	3 and 20	USPAT; US-PGPUB; EPO; JPO; DERWENT
10	BRS	L23	10	(elasticity near material) near4 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT
11	BRS	L24	6985	6313532.pn.(elasticity near (layer material))	USPAT; US-PGPUB; EPO; JPO; DERWENT
12	BRS	L25	1	6313532.pn. and (elasticity near (layer material))	USPAT; US-PGPUB; EPO; JPO; DERWENT
13	BRS	L26	17	3 and ((elastomer\$2 elasticity compliant) near4 particles)	USPAT; US-PGPUB; EPO; JPO; DERWENT
14	BRS	L27	7	(low adj elastic near modulus) near4 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT
15	BRS	L29	10	(low adj elastic) near3 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT
16	BRS	L28	12	(low adj elastic) near4 particles	USPAT; US-PGPUB; EPO; JPO; DERWENT

	Time Stamp	Comments	Error Definition	Errors
1	2002/03/01 07:16			0
2	2002/03/01 07:32			0
3	2002/03/01 07:41			0
4	2002/03/01 08:55			0
5	2002/03/01 07:59			0
6	2002/03/01 08:01			0
7	2002/03/01 08:04			0
8	2002/03/01 09:12			0
9	2002/03/01 08:57			0
10	2002/03/01 09:06			0
11	2002/03/01 09:07			0
12	2002/03/01 09:07			0
13	2002/03/01 09:22			0
14	2002/03/01 09:28			0
15	2002/03/01 09:29			0
16	2002/03/01 09:29			0